

AMENDMENTS TO THE CLAIMS

*insert RW 9/10/10*  
Please ~~amend~~ the first paragraph as follows:

—The present applicaton is the national stage of International Application No. PCT/EP03/10778 , which was filed on September 27, 2003, and which claims priority to German Patent application No. 102 45 398.5, filed September 29, 2002, which application is incorporated herein fully by this reference.—

Please amend the first paragraph following the description header as follows:

—The invention relates to an apparatus and a method for applying semiconductor chips to a plurality of substrates, in particular smartcard modules and flexboards, ~~as claimed in the preambles of claims 1 and 10.—~~

Please delete the KEY TO FIGURES and the subsequent text thereafter on page 20 of the application.